IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Informa	tion														
Company name* Compa				ompany unique ID			Unique ID Authority				Response Date*				
nsemi										2023-06-08					
ontact Name			Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Steward	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Represent	tative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
roduct-Env-Steward	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Requester	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Date	e Vers	sion	Manufacturing Site			Weight*	UOM	Unit Type	
		STK541U	JC60C-E	3phase inverter HI	C		2023-06-08			VN2			14300.0	mg	Each
	roccess Informatio		. 15		GED 020 14G	I D	D 1 D			1.6		The state of the s		CD CL	
, , , , , , , , , , , , , , , , , , ,		Terminal Base Alloy J-STD-020 MSL		L Rating	Peak Process Body Temperature Max Time at O C 30		Time at Peak	<u> </u>			cles				
'	(Sn) - annealed	C	U Alloy	IN	JA		0		JC.	30		secon	ids 3		
omments															
		•.•	1 6 .												
For more information	regarding material cor	nposition p	please refer t	page 3											

RoHS Material Composition Declaration			Declaration 7	Гуре *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.												
RoHS Declaration * 4 - Item(s	does not contain RoHS restricted substances	per the definition above except for sele	ted exemptions	Supplier Acceptance	* Accepted							
Exemption: 7c-I Electrical and electronic co	omponents containing lead in a glass or cera	mic other than dielectric ceramic in	apacitors, e.g. piezoelect	ronic devices, or in a glass or co	eramic matrix compound.							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.												
Supplier Digital Signature Ra	astislav Drska	E										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	4692.15	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		58.6519	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		231.323	mg
			В	Nickel (Ni)	7440-02-0		7.9767	mg
			Supplier	Acrylic resins	Proprietary Data		3.2845	mg
			Supplier	Copper (Cu)	7440-50-8		315.3125	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		2.3461	mg
			Supplier	Aluminum (Al)	7429-90-5		4073.2554	mg
Chip Parts	41.84	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.1715	mg
			Supplier	Silver (Ag)	7440-22-4		1.2678	mg
			Supplier	Epoxy resins	129915-35-1		0.3766	mg
			Supplier	Tin (Sn)	7440-31-5		1.1339	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.0628	mg
			Supplier	Platinum (Pt)	7440-06-4		0.0167	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.7866	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		4.1673	mg
			Supplier	Phenolic resins	Proprietary Data		0.0544	mg
			Supplier	Palladium (Pd)	7440-05-3		0.3305	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		26.0998	mg
			В	Nickel (Ni)	7440-02-0		2.8702	mg
			Supplier	Gold (Au)	7440-57-5		0.0167	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	0.0544	mg
			Supplier	Copper (Cu)	7440-50-8		2.1338	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.2971	mg
Die	29.41	mg	Supplier	Silicon (Si)	7440-21-3		29.41	mg
Lead Frame	749.45	mg	Supplier	Iron (Fe)	7439-89-6		0.6745	mg
			Supplier	Copper (Cu)	7440-50-8		748.6256	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1499	mg
Mold Compound-Black	8664.04	mg		Brominated epoxy resin	proprietary data		173.2808	mg
			Supplier	Phenolic Resin	Proprietary Data		519.8424	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		173.2808	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		259.9212	mg

			Supplier	Fused Silica (SiO2)	60676-86-0	866.404	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	606.4828	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	6064.8281	mg
Plating	16.12	mg	Supplier	Tin (Sn)	7440-31-5	8.4179	mg
			В	Nickel (Ni)	7440-02-0	7.7021	mg
Solder Ball	45.76	mg	Supplier	Silver (Ag)	7440-22-4	1.4048	mg
			Supplier	Tin (Sn)	7440-31-5	44.0211	mg
			В	Antimony (Sb)	7440-36-0	0.0092	mg
			Supplier	Copper (Cu)	7440-50-8	0.3249	mg
Wire Bond - Al	61.23	mg	Supplier	Aluminum (Al)	7429-90-5	61.23	mg